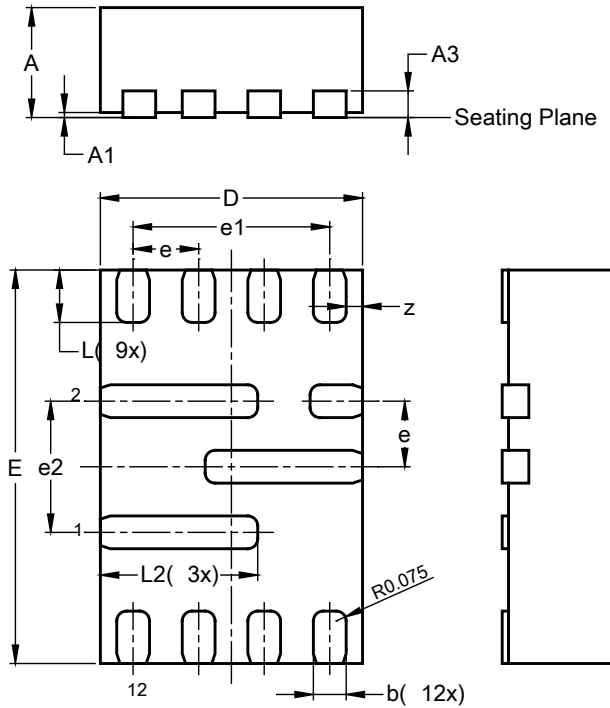


**Package Outline Dimensions**

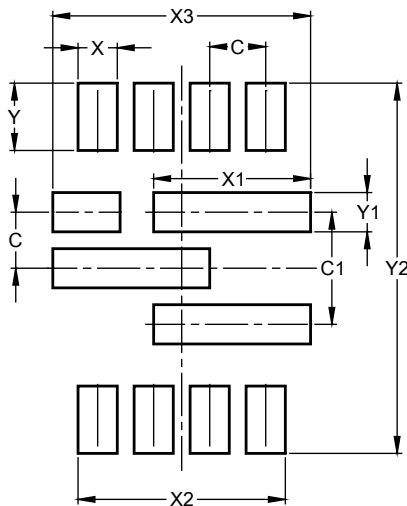
V-QFN2030-12 (Type A)



V-QFN2030-12 (Type A)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	—	—	0.203
b	0.20	0.30	0.25
D	1.95	2.05	2.00
E	2.95	3.05	3.00
e	0.50 BSC		
e1	1.50 BSC		
e2	1.00 BSC		
L	0.35	0.45	0.40
L2	1.15	1.25	1.20
z	—	—	0.125
All Dimensions in mm			

**Suggested Pad Layout**

V-QFN2030-12 (Type A)



Dimensions	Value (in mm)
C	0.500
C1	1.000
X	0.350
X1	1.400
X2	1.850
X3	2.300
Y	0.600
Y1	0.350
Y2	3.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.